



- NOTE:**
1. LEAD WIDTH & LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
  2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
  3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE
  4. LEAD COPLANARITY IS 0.003 INCH MAX.

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM	MAX.	MIN.	NOM	MAX.
A		1.20				.047
A1	0.05		0.15	.002		.006
A2	0.80	0.90	1.05	.031	.035	.041
L	0.50	0.60	0.75	.020	.024	.030
D	2.90	3.00	3.10	.114	.118	.122
E	6.30	6.40	6.50	.248	.252	.256
E1	4.30	4.40	4.50	.169	.173	.177
R	0.09			.004		
R1	0.09			.004		
b	0.19		0.30	.007		.012
b1	0.19	0.22	0.25	.007	.009	.010
c	0.09		0.20	.004		.008
c1	0.09		0.16	.004		.006
L1		1.0 REF.			.039 REF.	
e		0.65 BSC.			.026 BSC.	
theta 1	0		8	0		8
theta 2		12 REF.			12 REF.	
theta 3		12 REF.			12 REF.	
N			8			
REF		JEDEC MO-153 VARIATION AA				



TITLE:  
 PDD for 8 TSSOP(173MIL),  
 0.65MM PITCH

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 REV. B SHEET 1 OF 2



## Document History Page

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<b>Rev.</b>	<b>ECR No.</b>	<b>Date</b>	<b>Orig. of Change</b>	<b>Description of Change</b>
A	ECR-617	5/28/2008	RP	NEW RELEASE
B	ECR-713	8/4/2008	RP	NOTE COLUMN INCLUDED